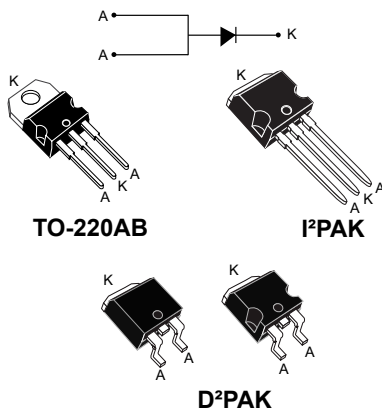


## 100 V, 30 A power Schottky rectifier



### Features

- High current capability
- Avalanche rated
- Low forward voltage drop
- High frequency operation
- **ECOPACK<sup>®</sup>2** compliant components (for D<sup>2</sup>PAK on demand)

### Applications

- Switching diode
- SMPS
- DC/DC converter
- LED lighting
- Desktop power supply

### Description

This single Schottky rectifier is suited for high frequency switch mode power supply.

Packaged in TO-220AB, D<sup>2</sup>PAK and I<sup>2</sup>PAK, the **STPS30SM100S** is optimized for use in notebook and game station adapters, providing in these applications a good efficiency at both low and high load.

#### Product status link

[STPS30SM100S](#)

#### Product summary

$I_{F(AV)}$	30 A
$V_{RRM}$	100 V
$T_j$ (max.)	150 °C
$V_F$ (typ.)	0.63 V

# 1 Characteristics

**Table 1. Absolute ratings (limiting values, with terminals 1 and 3 short circuited, at 25 °C, unless otherwise specified)**

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage	100	V	
I <sub>F(RMS)</sub>	Forward rms current	60	A	
I <sub>F(AV)</sub>	Average forward current $\delta = 0.5$ , square wave	T <sub>c</sub> = 125 °C	30	A
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal	400	A
P <sub>ARM</sub>	Repetitive peak avalanche power	t <sub>p</sub> = 10 $\mu$ s, T <sub>j</sub> = 125 °C	1545	W
T <sub>stg</sub>	Storage temperature range	-65 to +175	°C	
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup>	150	°C	

1.  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

**Table 2. Thermal resistance parameter**

Symbol	Parameter	Max. value	Unit
R <sub>th(j-c)</sub>	Junction to case	1	°C/W

For more information, please refer to the following application note:

- AN5088: Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics (with terminals 1 and 3 short circuited)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-		45	$\mu$ A
		T <sub>j</sub> = 125 °C		-	15	45	mA
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 5 A	-	500		mV
		T <sub>j</sub> = 125 °C		-	420		
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 10 A	-	600	670	
		T <sub>j</sub> = 125 °C		-	505	560	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 30 A	-	780	870	
		T <sub>j</sub> = 125 °C		-	630	690	

1. Pulse test: t<sub>p</sub> = 5 ms,  $\delta < 2\%$

2. Pulse test: t<sub>p</sub> = 380  $\mu$ s,  $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

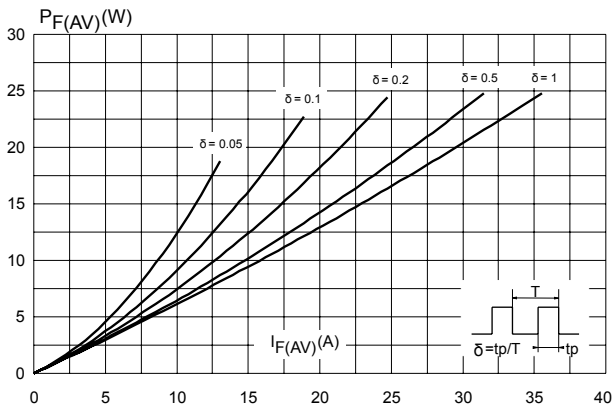
$$P = 0.580 \times I_{F(AV)} + 0.0033 \times I_F^2 (RMS)$$

For more information, please refer to the following application notes related to the power losses:

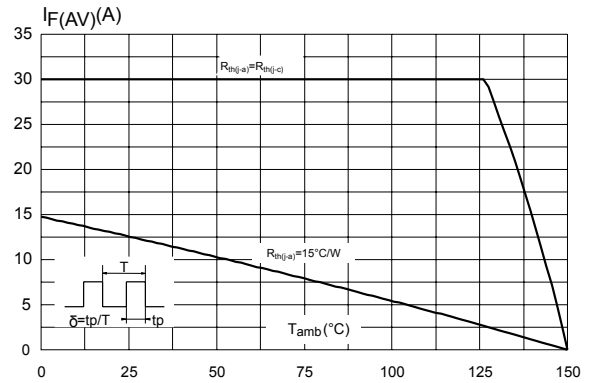
- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

## 1.1 Characteristics (curves)

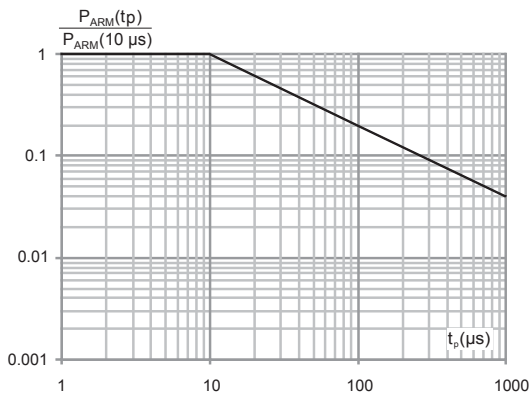
**Figure 1. Average forward power dissipation versus average forward current (terminals 1 and 3 short circuited)**



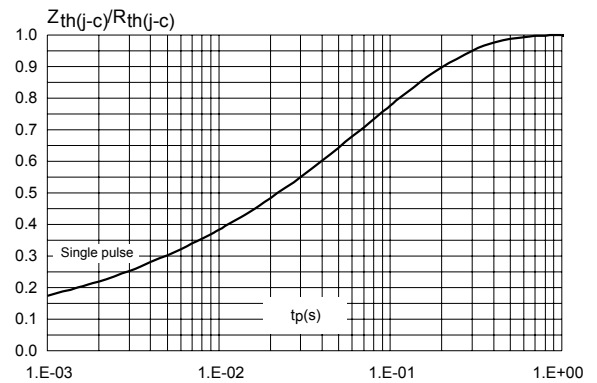
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ , terminals 1 and 3 short circuited)**



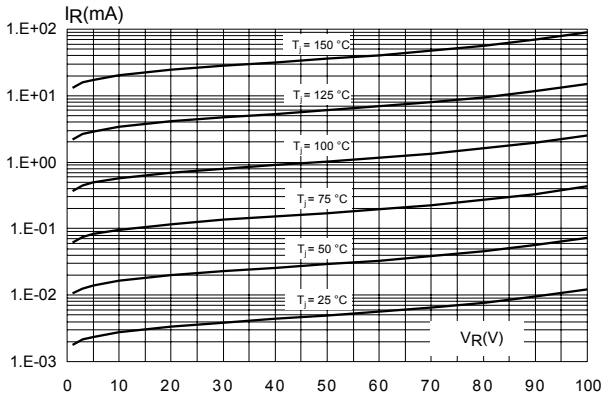
**Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j = 125^\circ\text{C}$ )**



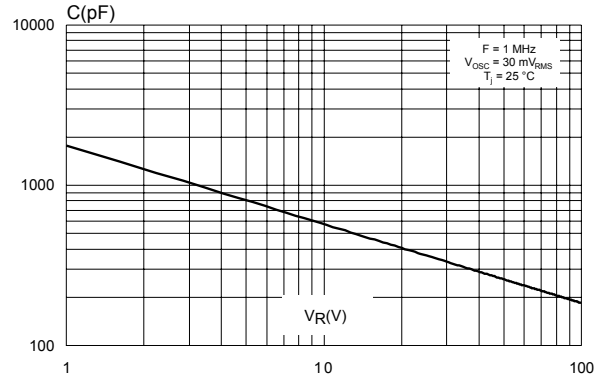
**Figure 4. Relative variation of thermal impedance junction to case versus pulse duration**



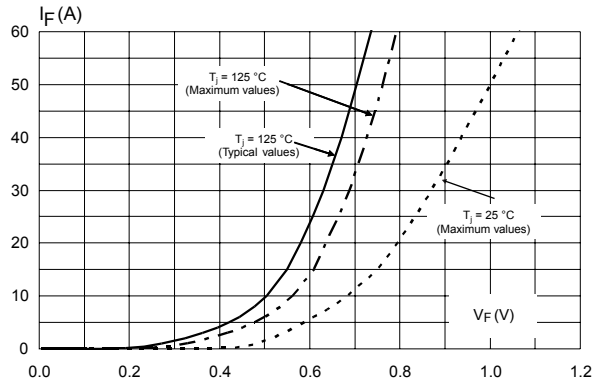
**Figure 5. Reverse leakage current versus reverse voltage applied (typical values)**



**Figure 6. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 7. Forward voltage drop versus forward current (terminals 1 and 3 short circuited)**



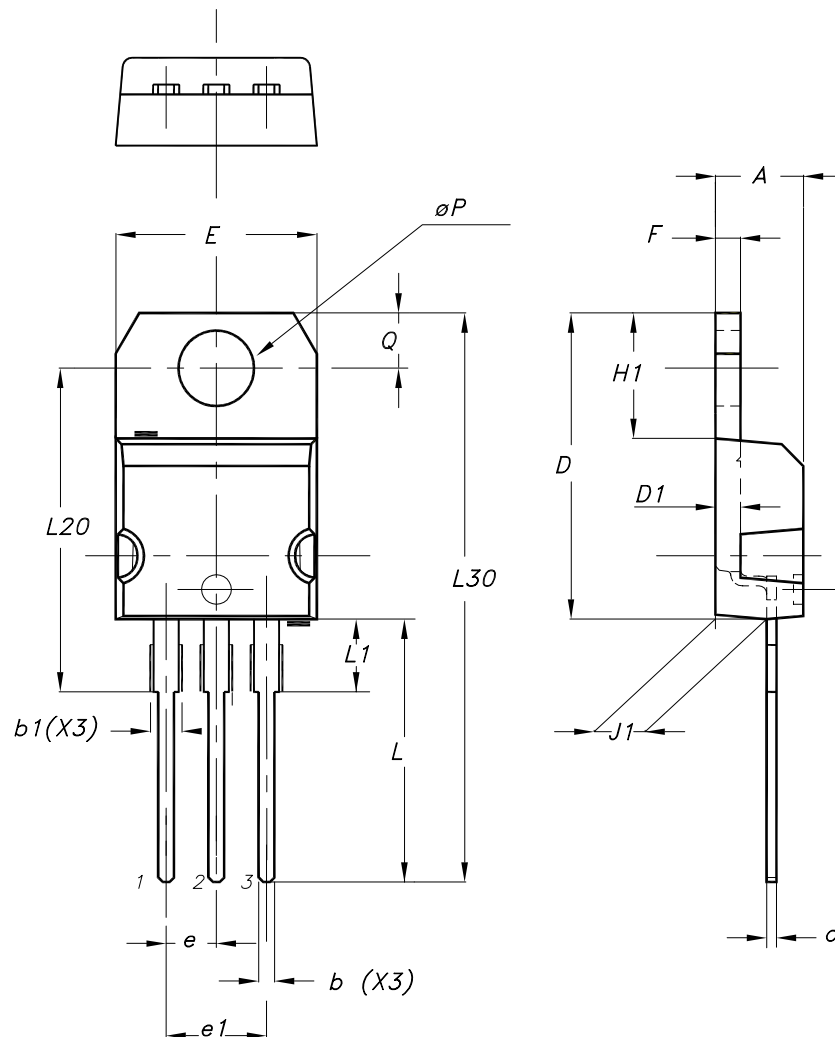
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK®** packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 TO-220AB package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.70 N·m

**Figure 8. TO-220AB package outline**



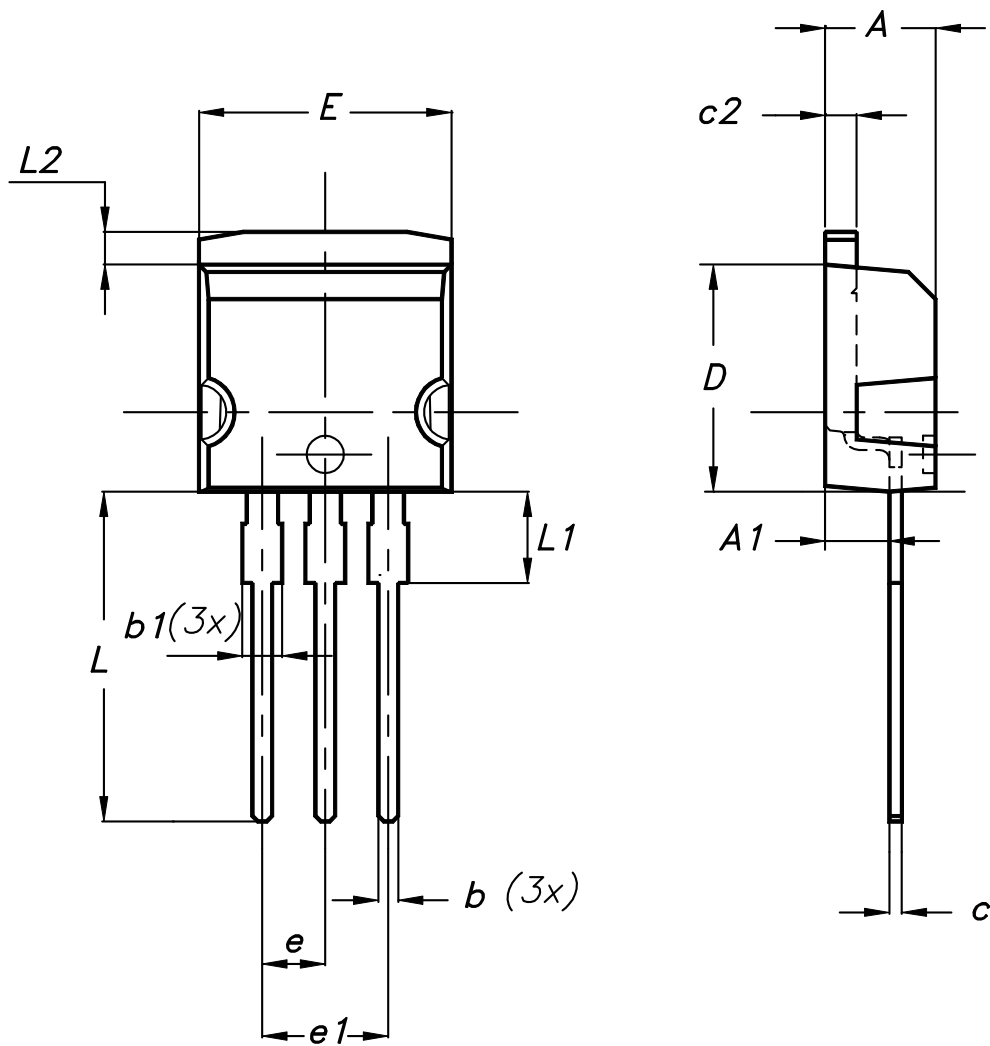
**Table 4. TO-220AB package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	0.61	0.88	0.240	0.035
b1	1.14	1.55	0.045	0.061
c	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
D1	1.27 typ.		0.050 typ.	
E	10.00	10.40	0.394	0.409
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.244	0.260
J1	2.40	2.72	0.094	0.107
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.90 typ.		1.138 typ.	
θP	3.75	3.85	0.148	0.152
Q	2.65	2.95	0.104	0.116

## 2.2 I<sup>2</sup>PAK package information

- Epoxy meets UL 94, V0
- Cooling method: by conduction (C)

Figure 9. I<sup>2</sup>PAK package outline



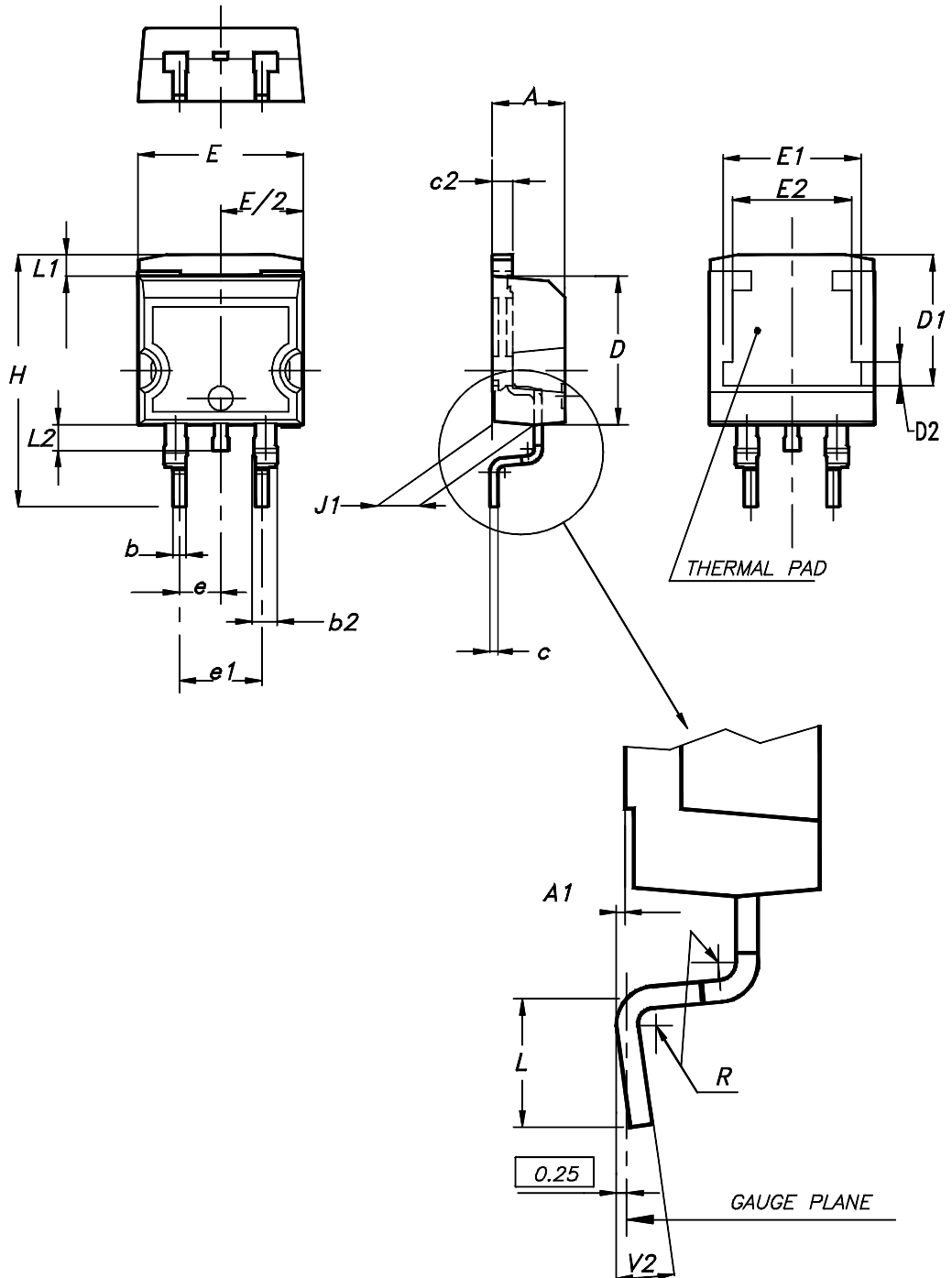
**Table 5. I<sup>2</sup>PAK package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.40	2.72	0.094	0.107
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.044	0.067
c	0.49	0.70	0.019	0.028
c2	1.23	1.32	0.048	0.052
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
E	10.00	10.40	0.394	0.409
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L2	1.27	1.40	0.050	0.055



### 2.3 D<sup>2</sup>PAK package information

Figure 10. D<sup>2</sup>PAK package outline

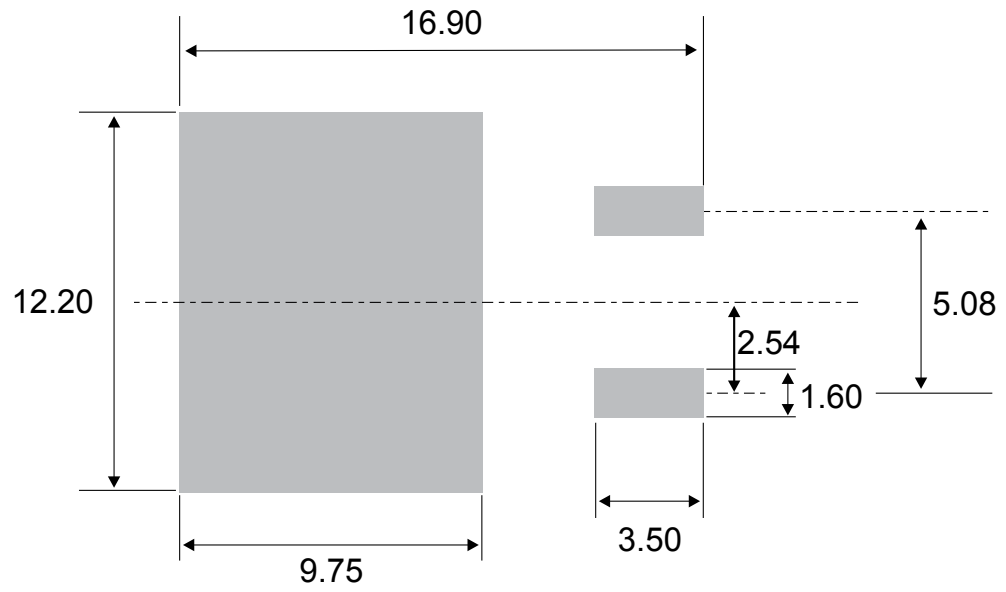


Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

**Table 6. D<sup>2</sup>PAK package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.36	4.60	0.172	0.181
A1	0.00	0.25	0.000	0.010
b	0.70	0.93	0.028	0.037
b2	1.14	1.70	0.045	0.067
c	0.38	0.69	0.015	0.027
c2	1.19	1.36	0.047	0.053
D	8.60	9.35	0.339	0.368
D1	6.90	8.00	0.272	0.311
D2	1.10	1.50	0.043	0.060
E	10.00	10.55	0.394	0.415
E1	8.10	8.90	0.319	0.346
E2	6.85	7.25	0.266	0.282
e	2.54 typ.		0.100	
e1	4.88	5.28	0.190	0.205
H	15.00	15.85	0.591	0.624
J1	2.49	2.90	0.097	0.112
L	1.90	2.79	0.075	0.110
L1	1.27	1.65	0.049	0.065
L2	1.30	1.78	0.050	0.070
R	0.4 typ.		0.015	
V2	0°	8°	0°	8°

**Figure 11. D<sup>2</sup>PAK recommended footprint (dimensions in mm)**



### 3 Ordering information

**Table 7. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS30SM100ST	PS30SM100ST	TO-220AB	1.95 g	50	Tube
STPS30SM100SR	PS30SM100SR	I <sup>2</sup> PAK	1.50 g	50	Tube
STPS30SM100SG-TR	PS30SM100SG	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel

## Revision history

**Table 8. Document revision history**

Date	Revision	Changes
25-Mar-2009	1	First issue.
16-Apr-2010	2	Updated package graphic for TO-220AB on front page and in <i>Table 5</i> .
28-Jan-2011	3	Added warning paragraph above <i>Table 8</i> .
15-Sep-2011	4	Added TO-220AB narrow leads package.
12-May-2017	5	Removed TO-220FPAB package. Updated D <sup>2</sup> PAK section.
05-Oct-2018	6	Updated cover page and <a href="#">Table 1</a> . Absolute ratings (limiting values, with terminals 1 and 3 short circuited, at 25 °C, unless otherwise specified). Removed figure 1, figure 9 and TO-220AB narrow leads package. Minor text changes to improve readability.
18-Feb-2019	7	Updated <a href="#">Table 1</a> .

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